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Abstract:

ABSTRACT

Disclosed is a phosphazene compound and a photosensitive resin composition. The phosphazene compound is obtained by reacting a phenoxyphosphazene compound (A-1) having a phenolic hydroxyl group and/or a cross-linked phenoxyphosphazene compound (A-2) obtained by cross-linking the phenoxyphosphazene compound (A-1) with an epoxy compound (B) having an unsaturated double bond and/or an isocyanate compound (C), wherein the phosphazene compound has an unsaturated double bond in its molecule. The photosensitive resin composition includes at least: a soluble polyimide resin (G-1) having a carboxyl group and/or a hydroxyl group and is soluble in an organic solvent, as the polyimide resins (G); and a phenoxyphosphazene compound (H-1) having a phenolic hydroxyl group and/or a cross-linked phenoxyphosphazene compound (H-2), which is obtained by cross-linking the phenoxyphosphazene compound (H-1) and has at least one phenolic hydroxyl group, as the phosphazene compound (H), and the photosensitive resin composition further includes a (meth)acrylic compound (L).